

EE130 Midterm #1 Fall 1998

Professor: C. Hu

Closed book; One sheet of notes allowed.

1. (16 pts) Consider a semiconductor for which:

$$n_i = 10^{13} \text{ /cm}^3$$

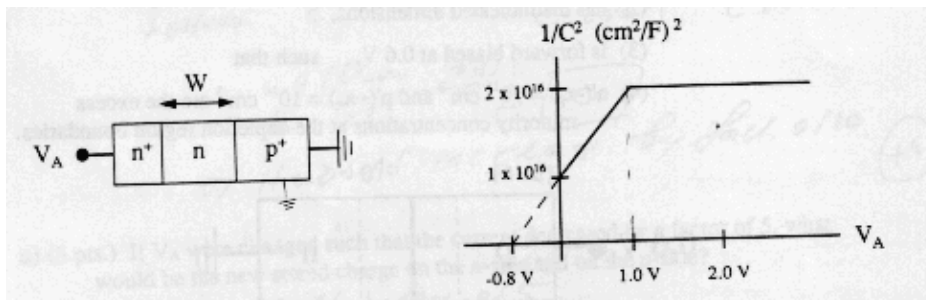
$$\mu_n = \mu_p = 25 \text{ cm}^2/\text{Vs}$$

$$\text{fixed mean scattering times } \tau_{scn} = \tau_{scp} = 10^{-12} \text{ s.}$$

$$N_d = 0.$$

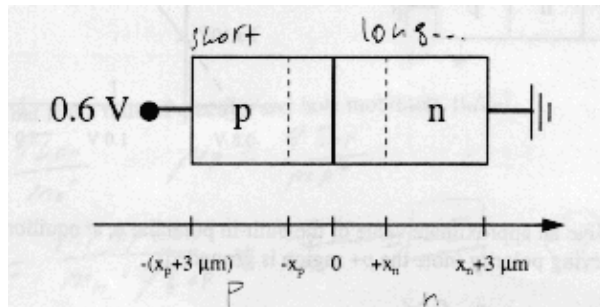
- 3pts. What is the ratio of electron and hole mobilities,  $\mu_n / \mu_p$
- 10pts. Determine the acceptor concentration  $N_a$  that would minimize total conductivity  $\sigma$ .
- 3pts. What is the electron diffusion coefficient  $D_n$  at room temperature?

2. (18 pts) Consider the plot of  $1/C^2$  vs. applied voltage  $V_A$  from the silicon  $n^+np^+$  diode pictured below. Doping concentrations are uniform throughout each of the  $n^+$ ,  $n$  and  $p^+$  regions.



- 2pts. Give an approximate value of the built-in potential  $\phi_{bi}$  at equilibrium, while observing polarity. note that the  $p_+$  region is grounded.
- 3pts. What is the depletion width  $x_{subd}$  at equilibrium?
- 8pts. What is the maximum electric field in the diode at  $V_A = 0\text{V}$ ?  
You may make appropriate approximations given the diode is a one-sided junction.
- 5pts. Determine the width  $W$  of the sandwiched  $n$ -region.

3. (30 pts) Consider the Si pn diode illustrated below. The diode is:
1. at room temperature
  2. has the indicated dimensions.
  3. is forward biased at .6V, such taht
  4.  $n'(-xp) = 10^{15} \text{ cm}^{-3}$  and  $p'(+xn) = 10^{14} \text{ cm}^{-3}$  are the excess minority concentrations at the depletion region boundaries.



- a) 7pts. You are given  $L_p = 100$  microns on the n-side and  $L_n = .1$  microns on the p-side. Compute the stored minority charge densities ( $\text{C}/\text{cm}^2$ ) on the n-side and on the p-side

(Hint: make appropriate approximations given the sizes of  $L_p$  and  $L_n$  relative to the diode dimensions).

- b) 6pts. You are asked to modify the diode design so as to improve its switching speed (i.e. reduce the stored charge for a given current).

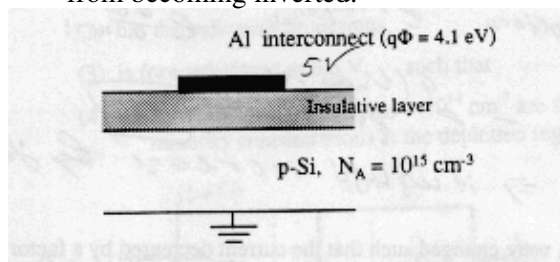
Suggest two changes you would make. Number the changes #1 and #2 according to their effectiveness.

- c) 5pts. If  $V_a$  were increased to .66 V by what factor would the current  $I$  increase?

- d) 5pts. If  $V_a$  were changed such that the current decreased by a factor of 5 what would be the new stored charge on the n-side and on the p-side.

- e) 7pts. If both n and p sides of the diode were shortened by 1 micron, by what factors would  $\text{abs}(J_n(-xp))$  and  $\text{abs}(J_p(xn))$  change?

4. (36 pts). Metal interconnect lines in IC circuits form parasitic MOS capacitors as illustrated below. Generally one wants to prevent the underlying Si substrate from becoming inverted.



- a) 6pts. Find  $V_{fb}$  for the parasitic MOS capacitor.
- b) 8pts. If the interconnect is at 5 V, what is the minimum capacitance ( $F/cm^2$ ) of the insulative layer to prevent inversion?
- c) 4pts. If for fabrication considerations the insulative layer thickness must be 1 micron, what should be the dielectric constant  $K = \epsilon/\epsilon_0$  of the insulative material to make  $V_t = 5V$ .
- d) 3pts. Is the answer in (c) the minimum for maximum allowable  $K$  to prevent inversion?
- e) 5pts. At  $V_g = V_t + 2V$  ( $V_t = 5V$ ) what would be the area charge density ( $C/cm^2$ ) of an inversion layer.
- f) 6pts. At  $V_g = V_t = 5V$  what would be the high-frequency MOS capacitance ( $F/cm^2$ )?
- g) 4pts. At  $V_g = V_t + 2V$  ( $V_t = 5V$ ) what voltage is dropped across the insulative layer?